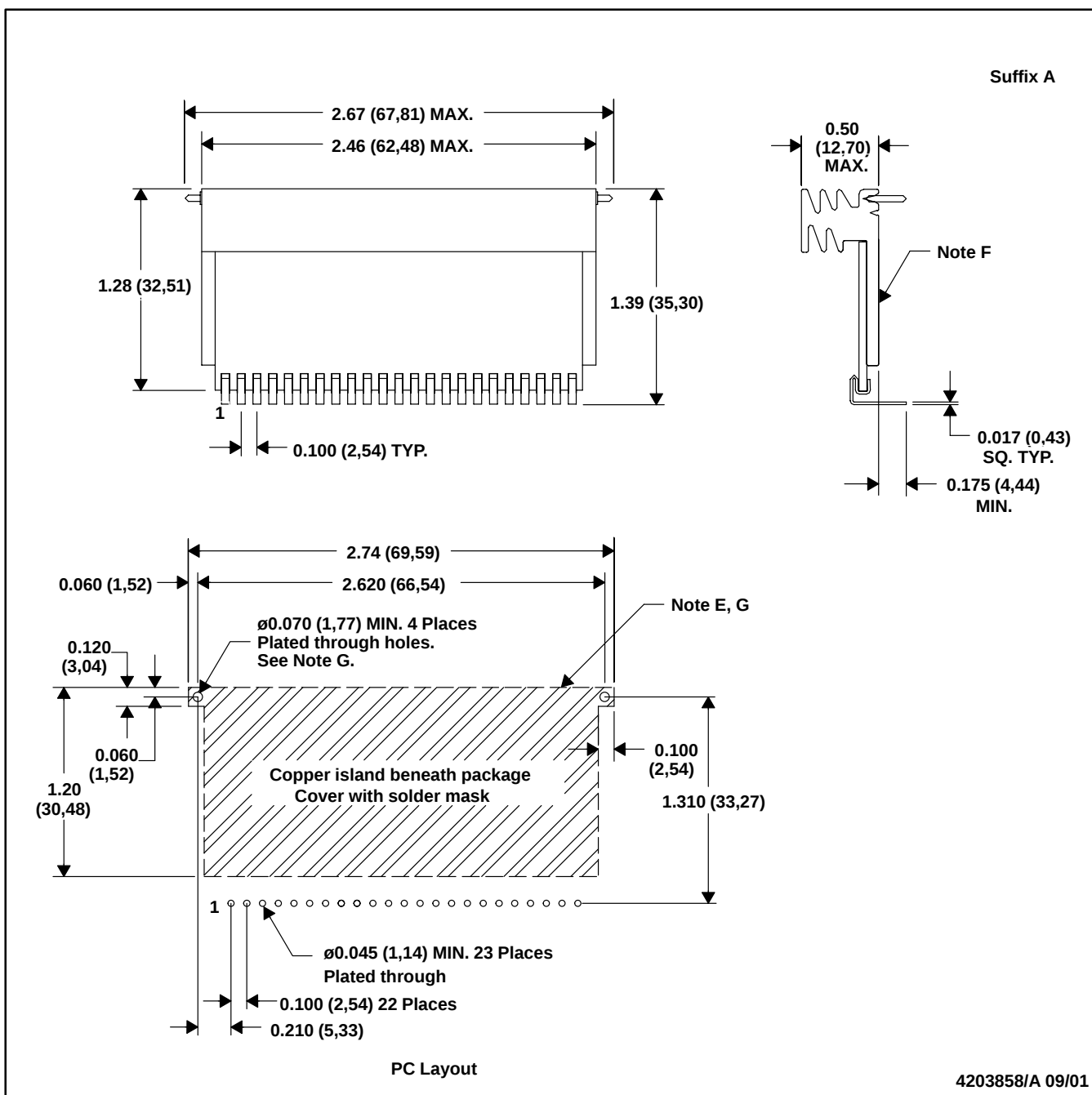


EJJ (R-MSIP-T23)

METAL SINGLE-IN-LINE MODULE



- NOTES: A. All linear dimensions are in inches (mm).
 B. This drawing is subject to change without notice.
 C. 2 place decimals are ± 0.030 ($\pm 0,76$ mm).
 D. 3 place decimals are ± 0.010 ($\pm 0,25$ mm).
 E. Recommended mechanical keep out area.
 F. The heatsink is isolated but electrically conductive.
 No signal traces are allowed under the heatsink area.
 A solid copper island is recommended, which may be connected to ground.
 G. Case outline reference.

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